

# MECHANICAL CASE OUTLINE

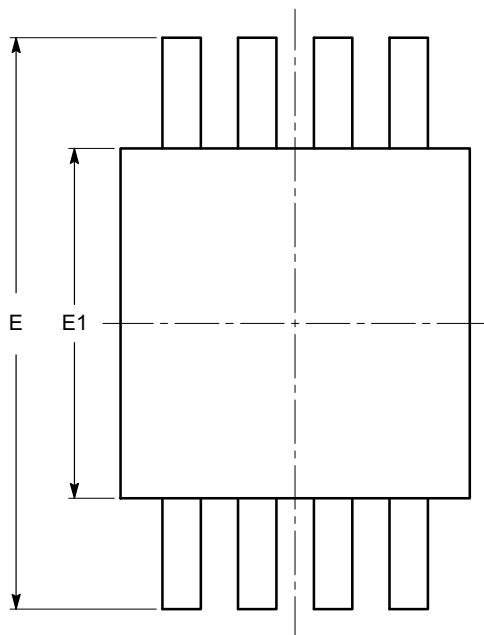
## PACKAGE DIMENSIONS

ON Semiconductor®



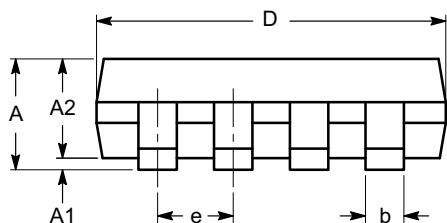
MSOP 8, 3x3  
CASE 846AD-01  
ISSUE O

DATE 19 DEC 2008

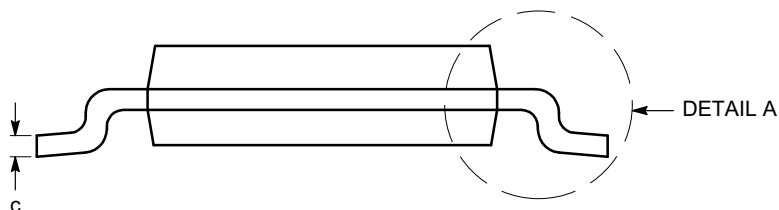


TOP VIEW

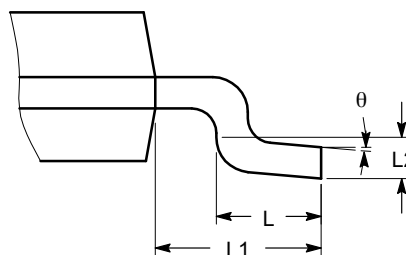
SYMBOL	MIN	NOM	MAX
A			1.10
A1	0.05	0.10	0.15
A2	0.75	0.85	0.95
b	0.22		0.38
c	0.13		0.23
D	2.90	3.00	3.10
E	4.80	4.90	5.00
E1	2.90	3.00	3.10
e	0.65 BSC		
L	0.40	0.60	0.80
L1	0.95 REF		
L2	0.25 BSC		
$\theta$	0°		6°



SIDE VIEW



END VIEW



DETAIL A

**Notes:**

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-187.

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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>REFERENCE:</b>		
<b>DESCRIPTION:</b>	MSOP 8, 3X3	<b>PAGE 1 OF 2</b>

